

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Tsung-Lin Lee</td> <td>03/13/2012</td> </tr> <tr> <td>Feng Yuan</td> <td>03/13/2012</td> </tr> <tr> <td>Chih Chieh Yeh</td> <td>03/13/2012</td> </tr> <tr> <td>Wei-Jen Lai</td> <td>03/13/2012</td> </tr> </tbody> </table>		Name	Execution Date	Tsung-Lin Lee	03/13/2012	Feng Yuan	03/13/2012	Chih Chieh Yeh	03/13/2012	Wei-Jen Lai	03/13/2012		
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
<p>Fax Number: (214)200-0853 Phone: 214-651-5000 Email: ipdocketing@haynesboone.com <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: Haynes and Boone LLP Address Line 1: 2323 Victory Avenue Address Line 2: Suite 700 Address Line 4: Dallas, TEXAS 75219</p>													
ATTORNEY DOCKET NUMBER:	24061.2027/2011-1298												
NAME OF SUBMITTER:	David M. O'Dell												
<p>Total Attachments: 3 source=24061-2027Assignment#page1.tif source=24061-2027Assignment#page2.tif source=24061-2027Assignment#page3.tif</p>													

OP \$40.00 13411304

PATENT

ASSIGNMENT

WHEREAS, we,

- (1) Tsung-Lin Lee of 6F., No. 19, Lane 634, Nanda Road, East District Hsinchu City 300, Taiwan R.O.C.
- (2) Feng Yuan of 8F.-7, No. 80, Section 1, Xiulang Road Yonghe City, Taipei County 234, Taiwan R.O.C.
- (3) Chih Chieh Yeh of 1F., No.122, Dajhih Street Jhongshan District, Taipei City 104, Taiwan R.O.C.
- (4) Wei-Jen Lai of 5F., No. 7, Alley 10, Lane 168, Zhonghe Road Zhongshan District, Keelung City 203, Taiwan R.O.C.

have invented certain improvements in

GATE STRUCTURE FOR SEMICONDUCTOR DEVICE

for which we have executed an application for Letters Patent of the United States of America, filed on March 2, 2012 and assigned application number 13/411,304; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional,

continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Tsung-Lin Lee

Residence Address: 6F., No. 19, Lane 634, Nanda Road, East District
Hsinchu City 300, Taiwan R.O.C.

Dated: ✓ 2012.03.13

✓ Tsung Lin Lee
Inventor Signature

Inventor Name: Feng Yuan

Residence Address: 8F.-7, No. 80, Section 1, Xiulang Road
Yonghe City, Taipei County 234, Taiwan R.O.C.

Dated: ✓ 2012.3.13.

✓ Feng Yuan
Inventor Signature

Inventor Name: Chih Chieh Yeh

Residence Address: 1F., No.122, Dajhih Street
Jhongshan District, Taipei City 104, Taiwan R.O.C.

Dated: ✓ 2012, 3.13

✓ Chih Chieh Yeh
Inventor Signature

Docket No.: 2011-1298 / 24061.2027

Customer No.: 42717

Inventor Name: Wei-Jen Lai

Residence Address: 5F., No. 7, Alley 10, Lane 168, Zhonghe Road
Zhongshan District, Keelung City 203, Taiwan R.O.C.

Dated: ✓ 2012.03.13

✓ Wei-Jen Lai
Inventor Signature
